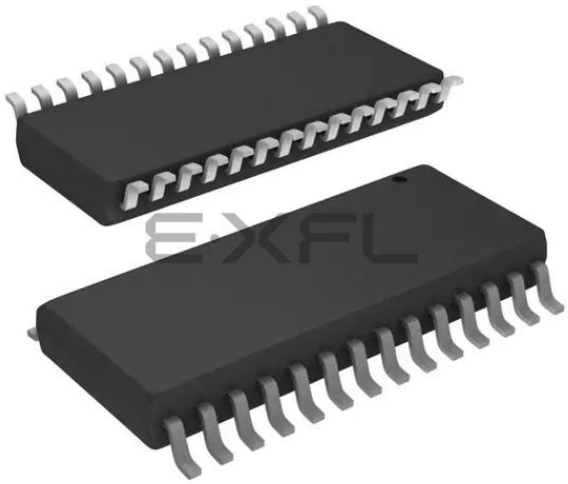

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2320-i-so

1.3 Details on Individual Family Members

Devices in the PIC18F2220/2320/4220/4320 family are available in 28-pin (PIC18F2X20) and 40/44-pin (PIC18F4X20) packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2.

The devices are differentiated from each other in five ways:

1. Flash program memory (4 Kbytes for PIC18FX220 devices, 8 Kbytes for PIC18FX320)
2. A/D channels (10 for PIC18F2X20 devices, 13 for PIC18F4X20 devices)
3. I/O ports (3 bidirectional ports and 1 input only port on PIC18F2X20 devices, 5 bidirectional ports on PIC18F4X20 devices)
4. CCP and Enhanced CCP implementation (PIC18F2X20 devices have 2 standard CCP modules, PIC18F4X20 devices have one standard CCP module and one ECCP module)
5. Parallel Slave Port (present only on PIC18F4X20 devices)

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

TABLE 1-1: DEVICE FEATURES

Features	PIC18F2220	PIC18F2320	PIC18F4220	PIC18F4320
Operating Frequency	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz
Program Memory (Bytes)	4096	8192	4096	8192
Program Memory (Instructions)	2048	4096	2048	4096
Data Memory (Bytes)	512	512	512	512
Data EEPROM Memory (Bytes)	256	256	256	256
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C (E)	Ports A, B, C (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/ Compare/PWM Modules	0	0	1	1
Serial Communications	MSSP, Addressable USART	MSSP, Addressable USART	MSSP, Addressable USART	MSSP, Addressable USART
Parallel Communications (PSP)	No	No	Yes	Yes
10-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Resets (and Delays)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT
Programmable Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions	75 Instructions	75 Instructions	75 Instructions
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN

2.6.2 OSCTUNE REGISTER

The internal oscillator block is calibrated at the factory to produce an INTOSC output frequency of approximately 8 MHz. (See parameters F14–F19 in Table 26-8.)

The INTOSC frequency can be adjusted using the TUN5:TUN1 bits in the OSCTUNE register OSCTUNE<5:1>. OSCTUNE<0> has no effect, but is readable and writable, enabling changes of the INTOSC frequency using two increment or decrement instructions.

The internal oscillator's output can be adjusted in the user's application. This is done by writing to the OSCTUNE register (Register 2-1). The tuning sensitivity is constant throughout the tuning range.

When the OSCTUNE register is modified, the INTOSC and INTRC frequencies begin shifting to the new frequency. The INTOSC and INTRC clocks will stabilize at the new frequency within 100 μs. Code execution continues during this shift.

There is no indication when the shift occurs. Operation of features that depend on the INTRC clock source frequency also will be affected by the change in frequency. This includes the WDT, Fail-Safe Clock Monitor and peripherals.

REGISTER 2-1: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-1 **TUN<5:1>:** Frequency Tuning bits – Adjusts the frequency of INTOSC. Can adjust INTRC, depending on TUNSEL (OSCTUN2<7>)

011111 = Maximum frequency
•
•
000001
000000 = Center frequency. Oscillator module is running at the calibrated frequency.
111111
•
•
100000 = Minimum frequency

bit 0 **TUN<0>:** A placeholder with no effect on the INTRC frequency. Provided to facilitate incrementation and decrementation of the OSCTUN2 register and adjustment of the INTRC frequency.

NOTES:

5.2 Return Address Stack

The return address stack allows any combination of up to 31 program calls and interrupts to occur. The PC (Program Counter) is pushed onto the stack when a CALL or RCALL instruction is executed or an interrupt is Acknowledged. The PC value is pulled off the stack on a RETURN, RETLW or a RETFIE instruction. PCLATU and PCLATH are not affected by any of the RETURN or CALL instructions.

The stack operates as a 31-word by 21-bit RAM and a 5-bit Stack Pointer, with the Stack Pointer initialized to 00000b after all Resets. There is no RAM associated with Stack Pointer, 00000b. This is only a Reset value. During a CALL type instruction, causing a push onto the stack, the Stack Pointer is first incremented and the RAM location pointed to by the Stack Pointer is written with the contents of the PC (already pointing to the instruction following the CALL). During a RETURN type instruction, causing a pop from the stack, the contents of the RAM location pointed to by the STKPTR are transferred to the PC and then the Stack Pointer is decremented.

The stack space is not part of either program or data space. The Stack Pointer is readable and writable and the address on the top of the stack is readable and writable through the top-of-stack Special File Registers. Data can also be pushed to, or popped from, the stack using the top-of-stack SFRs. Status bits indicate if the stack is full, has overflowed or underflowed.

5.2.1 TOP-OF-STACK ACCESS

The top of the stack is readable and writable. Three register locations, TOSU, TOSH and TOSL, hold the contents of the stack location pointed to by the STKPTR register (Figure 5-3). This allows users to implement a software stack if necessary. After a CALL, RCALL or interrupt, the software can read the pushed value by reading the TOSU, TOSH and TOSL registers. These values can be placed on a user-defined software stack. At return time, the software can replace the TOSU, TOSH and TOSL and do a return.

The user must disable the global interrupt enable bits while accessing the stack to prevent inadvertent stack corruption.

5.2.2 RETURN STACK POINTER (STKPTR)

The STKPTR register (Register 5-1) contains the Stack Pointer value, the STKFUL (Stack Full) status bit and the STKUNF (Stack Underflow) status bits. The value of the Stack Pointer can be 0 through 31. The Stack Pointer increments before values are pushed onto the stack and decrements after values are popped off the stack. At Reset, the Stack Pointer value will be zero. The user may read and write the Stack Pointer value. This feature can be used by a Real-Time Operating System for return stack maintenance.

After the PC is pushed onto the stack 31 times (without popping any values off the stack), the STKFUL bit is set. The STKFUL bit is cleared by software or by a POR.

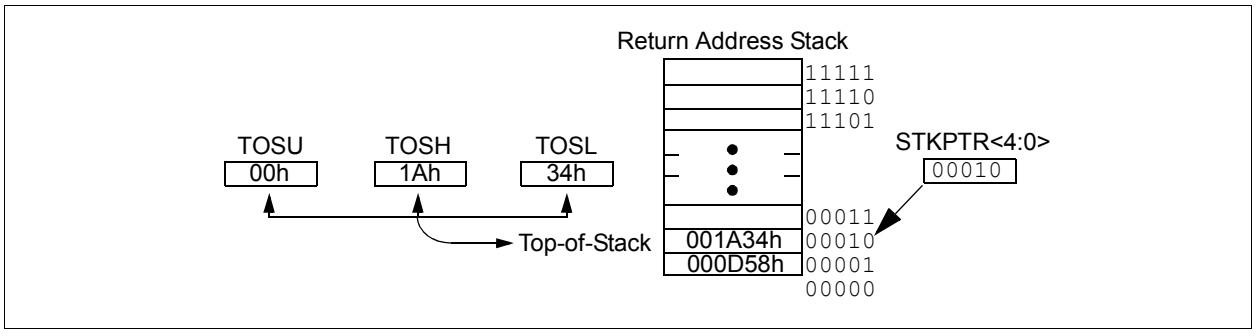
The action that takes place when the stack becomes full depends on the state of the STVREN (Stack Overflow Reset Enable) Configuration bit. (Refer to **Section 23.1 "Configuration Bits"** for a description of the device Configuration bits.) If STVREN is set (default), the 31st push will push the (PC + 2) value onto the stack, set the STKFUL bit and reset the device. The STKFUL bit will remain set and the Stack Pointer will be set to zero.

If STVREN is cleared, the STKFUL bit will be set on the 31st push and the Stack Pointer will increment to 31. Any additional pushes will not overwrite the 31st push, and STKPTR will remain at 31.

When the stack has been popped enough times to unload the stack, the next pop will return a value of zero to the PC and sets the STKUNF bit, while the Stack Pointer remains at zero. The STKUNF bit will remain set until cleared by software or a POR occurs.

Note:	Returning a value of zero to the PC on an underflow has the effect of vectoring the program to the Reset vector, where the stack conditions can be verified and appropriate actions can be taken. This is not the same as a Reset, as the contents of the SFRs are not affected.

FIGURE 5-3: RETURN ADDRESS STACK AND ASSOCIATED REGISTERS



7.3 Reading the Data EEPROM Memory

To read a data memory location, the user must write the address to the EEADR register, clear the EEPGD control bit (EECON1<7>) and then set control bit, RD (EECON1<0>). The data is available for the very next instruction cycle; therefore, the EEDATA register can be read by the next instruction. EEDATA will hold this value until another read operation or until it is written to by the user (during a write operation).

7.4 Writing to the Data EEPROM Memory

To write an EEPROM data location, the address must first be written to the EEADR register and the data written to the EEDATA register. The sequence in Example 7-2 must be followed to initiate the write cycle.

The write will not begin if this sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. It is strongly recommended that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable writes. This mechanism prevents accidental writes to data EEPROM due to unexpected code execution (i.e., runaway programs). The WREN bit should be kept clear at all times except when updating the EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, EECON1, EEADR and EEDATA cannot be modified. The WR bit will be inhibited from being set unless the WREN bit is set. The WREN bit must be set on a previous instruction. Both WR and WREN cannot be set with the same instruction.

At the completion of the write cycle, the WR bit is cleared in hardware and the EEPROM Interrupt Flag bit (EEIF) is set. The user may either enable this interrupt or poll this bit. EEIF must be cleared by software.

7.5 Write Verify

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

7.6 Protection Against Spurious Write

There are conditions when the device may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built-in. On power-up, the WREN bit is cleared. Also, the Power-up Timer (72 ms duration) prevents EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during brown-out, power glitch, or software malfunction.

EXAMPLE 7-1: DATA EEPROM READ

```
        MOVLW   DATA_EE_ADDR        ;
        MOVWF   EEADR               ; Data Memory Address to read
        BCF     EECON1, EEPGD       ; Point to DATA memory
        BSF     EECON1, RD          ; EEPROM Read
        MOVF    EEDATA, W           ; W = EEDATA
```

EXAMPLE 7-2: DATA EEPROM WRITE

```
            MOVLW   DATA_EE_ADDR        ;
            MOVWF   EEADR               ; Data Memory Address to write
            MOVLW   DATA_EE_DATA        ;
            MOVWF   EEDATA              ; Data Memory Value to write
            BCF     EECON1, EEPGD       ; Point to DATA memory
            BSF     EECON1, WREN        ; Enable writes
            BCF     INTCON, GIE         ; Disable Interrupts
            MOVLW   55h                 ;
Required    MOVWF   EECON2              ; Write 55h
Sequence    MOVLW   AAh                 ;
            MOVWF   EECON2              ; Write AAh
            BSF     EECON1, WR          ; Set WR bit to begin write
            BSF     INTCON, GIE         ; Enable Interrupts

            SLEEP                       ; Wait for interrupt to signal write complete
            BCF     EECON1, WREN        ; Disable writes
```

7.7 Operation During Code-Protect

Data EEPROM memory has its own code-protect bits in Configuration Words. External read and write operations are disabled if either of these mechanisms are enabled.

The microcontroller itself can both read and write to the internal Data EEPROM regardless of the state of the code-protect Configuration bit. Refer to **Section 23.0 "Special Features of the CPU"** for additional information.

7.8 Using the Data EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). Frequently changing values will typically be updated more often than specification D124 or D124A. If this is not the case, an array refresh must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

A simple data EEPROM refresh routine is shown in Example 7-3.

Note:	If data EEPROM is only used to store constants and/or data that changes rarely, an array refresh is likely not required. See specification D124 or D124A.

EXAMPLE 7-3: DATA EEPROM REFRESH ROUTINE

```
        CLRF    EEADR                   ; Start at address 0
        BCF     EECON1, CFGS            ; Set for memory
        BCF     EECON1, EEPGD           ; Set for Data EEPROM
        BCF     INTCON, GIE             ; Disable interrupts
        BSF     EECON1, WREN            ; Enable writes
LOOP                                    ; Loop to refresh array
        BSF     EECON1, RD              ; Read current address
        MOVLW   55h                     ;
        MOVWF   EECON2                  ; Write 55h
        MOVLW   AAh                     ;
        MOVWF   EECON2                  ; Write AAh
        BSF     EECON1, WR              ; Set WR bit to begin write
        BTFSC   EECON1, WR              ; Wait for write to complete
        BRA     $-2
        INCFSZ  EEADR, F                ; Increment address
        BRA     Loop                    ; Not zero, do it again

        BCF     EECON1, WREN            ; Disable writes
        BSF     INTCON, GIE             ; Enable interrupts
```

TABLE 7-1: REGISTERS ASSOCIATED WITH DATA EEPROM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
EEADR	EEPROM Address Register								0000 0000	0000 0000
EEDATA	EEPROM Data Register								0000 0000	0000 0000
EECON2	EEPROM Control Register 2 (not a physical register)								—	—
EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	xx-0 x000	uu-0 u000
IPR2	OSCFIP	CMIP	—	EEIP	BCLIP	LVDIP	TMR3IP	CCP2IP	11-1 1111	---1 1111
PIR2	OSCFIF	CMIF	—	EEIF	BCLIF	LVDIF	TMR3IF	CCP2IF	00-0 0000	---0 0000
PIE2	OSCFIE	CMIE	—	EEIE	BCLIE	LVDIE	TMR3IE	CCP2IE	00-0 0000	---0 0000

Legend: x = unknown, u = unchanged, r = reserved, - = unimplemented, read as '0'.
Shaded cells are not used during Flash/EEPROM access.

9.5 RCON Register

The RCON register contains bits used to determine the cause of the last Reset or wake-up from power-managed mode. RCON also contains the bit that enables interrupt priorities (IPEN).

REGISTER 9-10: RCON: RESET CONTROL REGISTER

R/W-0	U-0	U-0	R/W-1	R-1	R-1	R/W-0	R/W-0
IPEN	—	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IPEN:** Interrupt Priority Enable bit
1 = Enable priority levels on interrupts
0 = Disable priority levels on interrupts (PIC16CXXX Compatibility mode)

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{RI}$:** RESET Instruction Flag bit
1 = The RESET instruction was not executed (set by firmware only)
0 = The RESET instruction was executed causing a device Reset (must be set in software after a Brown-out Reset occurs)

bit 3 **$\overline{TO}$:** Watchdog Time-out Flag bit
1 = Set by power-up, CLRWDT instruction or SLEEP instruction
0 = A WDT time-out occurred

bit 2 **$\overline{PD}$:** Power-Down Detection Flag bit
1 = Set by power-up or by the CLRWDT instruction
0 = Cleared by execution of the SLEEP instruction

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
1 = A Power-on Reset has not occurred (set by firmware only)
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
1 = A Brown-out Reset has not occurred (set by firmware only)
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

TABLE 10-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit 0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input.
RC1/T1OSI/CCP2	bit 1	ST	Input/output port pin, Timer1 oscillator input or Capture 2 input/ Compare 2 output/PWM output when CCP2MX Configuration bit is disabled.
RC2/CCP1/P1A(1)	bit 2	ST	Input/output port pin, Capture 1 input/Compare 1 output/PWM1 output or Enhanced PWM output A(1).
RC3/SCK/SCL	bit 3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C™ modes.
RC4/SDI/SDA	bit 4	ST	RC4 can also be the SPI data in (SPI mode) or data I/O (I^2C mode).
RC5/SDO	bit 5	ST	Input/output port pin or Master Synchronous Serial Port data output.
RC6/TX/CK	bit 6	ST	Input/output port pin, addressable USART asynchronous transmit or addressable USART synchronous clock.
RC7/RX/DT	bit 7	ST	Input/output port pin, addressable USART asynchronous receive or addressable USART synchronous data.

Legend: ST = Schmitt Trigger input

Note 1: Enhanced PWM output is available only on PIC18F4X20 devices.

TABLE 10-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
LATC	LATC Data Latch Register								xxxx xxxx	uuuu uuuu
TRISC	PORTC Data Direction Register								1111 1111	1111 1111

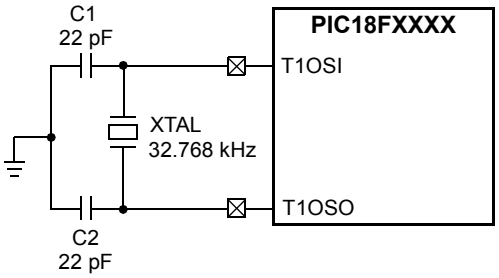
Legend: x = unknown, u = unchanged

12.2 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins, T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit, T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator rated for 32 kHz crystals. It will continue to run during all power-managed modes. The circuit for a typical LP oscillator is shown in Figure 12-3. Table 12-1 shows the capacitor selection for the Timer1 oscillator.

The user must provide a software time delay to ensure proper start-up of the Timer1 oscillator.

FIGURE 12-3: EXTERNAL COMPONENTS FOR THE TIMER1 LP OSCILLATOR



Note: See the Notes with Table 12-1 for additional information about capacitor selection.

TABLE 12-1: CAPACITOR SELECTION FOR THE TIMER OSCILLATOR(2,3,4)

Osc Type	Freq	C1	C2
LP	32 kHz	22 pF(1)	22 pF(1)

Note 1: Microchip suggests this value as a starting point in validating the oscillator circuit.

2: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Capacitor values are for design guidance only.

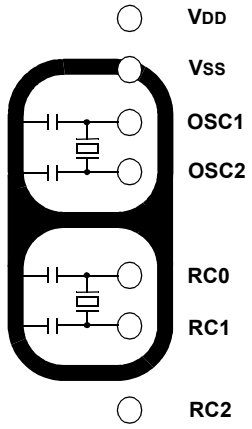
12.3 Timer1 Oscillator Layout Considerations

The Timer1 oscillator circuit draws very little power during operation. Due to the low-power nature of the oscillator, it may also be sensitive to rapidly changing signals in close proximity.

The oscillator circuit, shown in Figure 12-3, should be located as close as possible to the microcontroller. There should be no circuits passing within the oscillator circuit boundaries other than VSS or VDD.

If a high-speed circuit must be located near the oscillator (such as the CCP1 pin in output compare or PWM mode, or the primary oscillator using the OSC2 pin), a grounded guard ring around the oscillator circuit, as shown in Figure 12-4, may be helpful when used on a single-sided PCB or in addition to a ground plane.

FIGURE 12-4: OSCILLATOR CIRCUIT WITH GROUNDED GUARD RING



Note: Not drawn to scale.

17.4.4 CLOCK STRETCHING

Both 7 and 10-bit Slave modes implement automatic clock stretching during a transmit sequence.

The SEN bit (SSPCON2<0>) allows clock stretching to be enabled during receives. Setting SEN will cause the SCL pin to be held low at the end of each data receive sequence.

17.4.4.1 Clock Stretching for 7-Bit Slave Receive Mode (SEN = 1)

In 7-Bit Slave Receive mode, on the falling edge of the ninth clock at the end of the ACK sequence if the BF bit is set, the CKP bit in the SSPCON1 register is automatically cleared, forcing the SCL output to be held low. The CKP being cleared to '0' will assert the SCL line low. The CKP bit must be set in the user's ISR before reception is allowed to continue. By holding the SCL line low, the user has time to service the ISR and read the contents of the SSPBUF before the master device can initiate another receive sequence. This will prevent buffer overruns from occurring (see Figure 17-13).

Note 1: If the user reads the contents of the SSPBUF before the falling edge of the ninth clock, thus clearing the BF bit, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software regardless of the state of the BF bit. The user should be careful to clear the BF bit in the ISR before the next receive sequence in order to prevent an overflow condition.

17.4.4.2 Clock Stretching for 10-Bit Slave Receive Mode (SEN = 1)

In 10-Bit Slave Receive mode, during the address sequence, clock stretching automatically takes place but the CKP bit is not cleared. During this time, if the UA bit is set after the ninth clock, clock stretching is initiated. The UA bit is set after receiving the upper byte of the 10-bit address and following the receive of the second byte of the 10-bit address with the R/$\overline{W}$ bit cleared to '0'. The release of the clock line occurs upon updating SSPADD. Clock stretching will occur on each data receive sequence as described in 7-bit mode.

Note: If the user polls the UA bit and clears it by updating the SSPADD register before the falling edge of the ninth clock occurs and if the user hasn't cleared the BF bit by reading the SSPBUF register before that time, then the CKP bit will still NOT be asserted low. Clock stretching on the basis of the state of the BF bit only occurs during a data sequence, not an address sequence.

17.4.4.3 Clock Stretching for 7-Bit Slave Transmit Mode

7-Bit Slave Transmit mode implements clock stretching by clearing the CKP bit after the falling edge of the ninth clock if the BF bit is clear. This occurs regardless of the state of the SEN bit.

The user's ISR must set the CKP bit before transmission is allowed to continue. By holding the SCL line low, the user has time to service the ISR and load the contents of the SSPBUF before the master device can initiate another transmit sequence (see Figure 17-9).

Note 1: If the user loads the contents of SSPBUF, setting the BF bit before the falling edge of the ninth clock, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software regardless of the state of the BF bit.

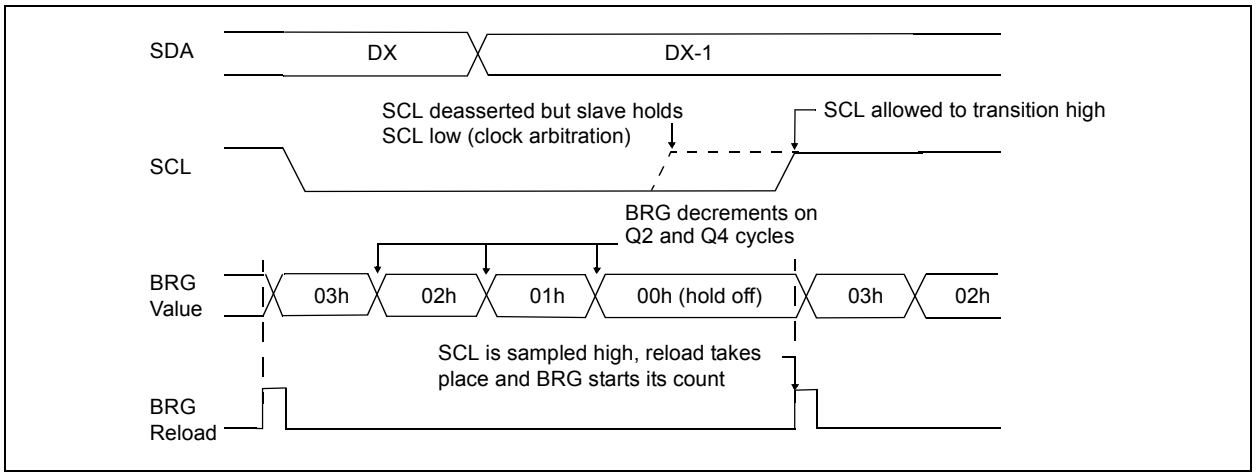
17.4.4.4 Clock Stretching for 10-Bit Slave Transmit Mode

In 10-Bit Slave Transmit mode, clock stretching is controlled during the first two address sequences by the state of the UA bit, just as it is in 10-Bit Slave Receive mode. The first two addresses are followed by a third address sequence which contains the high-order bits of the 10-bit address and the R/$\overline{W}$ bit set to '1'. After the third address sequence is performed, the UA bit is not set, the module is now configured in Transmit mode and clock stretching is controlled by the BF flag as in 7-Bit Slave Transmit mode (see Figure 17-11).

17.4.7.2 Clock Arbitration

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, deasserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 17-18).

FIGURE 17-18: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION



19.3 Selecting and Configuring Automatic Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set.

When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This occurs when the ACQT2:ACQT0 bits (ADCON2<5:3>) remain in their Reset state ('000') and is compatible with devices that do not offer programmable acquisition times.

If desired, the ACQT bits can be set to select a programmable acquisition time for the A/D module. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

19.4 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 11 TAD per 10-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (approximately 2 μs, see parameter #130 for more information).

Table 19-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 19-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Maximum Device Frequency	
Operation	**ADCS2:ADCS0**	**PIC18FXX20**	**PIC18LFXX20(4)**
2 TOSC	000	1.25 MHz	666 kHz
4 TOSC	100	2.50 MHz	1.33 MHz
8 TOSC	001	5.00 MHz	2.66 MHz
16 TOSC	101	10.0 MHz	5.33 MHz
32 TOSC	010	20.0 MHz	10.65 MHz
64 TOSC	110	40.0 MHz	21.33 MHz
RC(3)	x11	1.00 MHz(1)	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 4 μs.

2: The RC source has a typical TAD time of 6 μs.

3: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or the A/D accuracy may be out of specification.

4: Low-power devices only.

REGISTER 23-1: CONFIG1H: CONFIGURATION REGISTER 1 HIGH (BYTE ADDRESS 300001h)

R/P-1	R/P-1	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1
IESO	FSCM	—	—	FOSC3	FOSC2	FOSC1	FOSC0
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 **IESO:** Internal/External Switchover bit
1 = Internal/External Switchover mode enabled
0 = Internal/External Switchover mode disabled

bit 6 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor enabled
0 = Fail-Safe Clock Monitor disabled

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **FOSC3:FOSC0:** Oscillator Selection bits(1)
11xx = External RC oscillator, CLKO function on RA6
1001 = Internal oscillator block, CLKO function on RA6 and port function on RA7
1000 = Internal oscillator block, port function on RA6 and port function on RA7
0111 = External RC oscillator, port function on RA6
0110 = HS oscillator, PLL enabled (clock frequency = 4 x FOSC1)
0101 = EC oscillator, port function on RA6
0100 = EC oscillator, CLKO function on RA6
0010 = HS oscillator
0001 = XT oscillator
0000 = LP oscillator

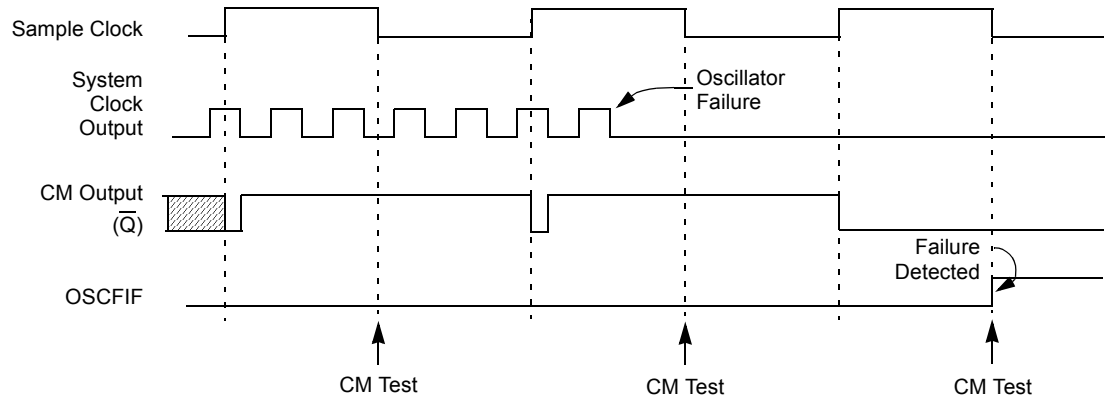
23.4.2 EXITING FAIL-SAFE OPERATION

The fail-safe condition is terminated by either a device Reset or by entering a power-managed mode. On Reset, the controller starts the primary clock source specified in Configuration Register 1H (with any required start-up delays that are required for the oscillator mode, such as OST or PLL timer). The INTOSC multiplexer provides the system clock until the primary clock source becomes ready (similar to a Two-speed Start-up). The clock system source is then switched to the primary clock (indicated by the OSTS bit in the OSCCON register becoming set). The Fail-Safe Clock Monitor then resumes monitoring the peripheral clock.

The primary clock source may never become ready during start-up. In this case, operation is clocked by the INTOSC multiplexer. The OSCCON register will remain in its Reset state until a power-managed mode is entered.

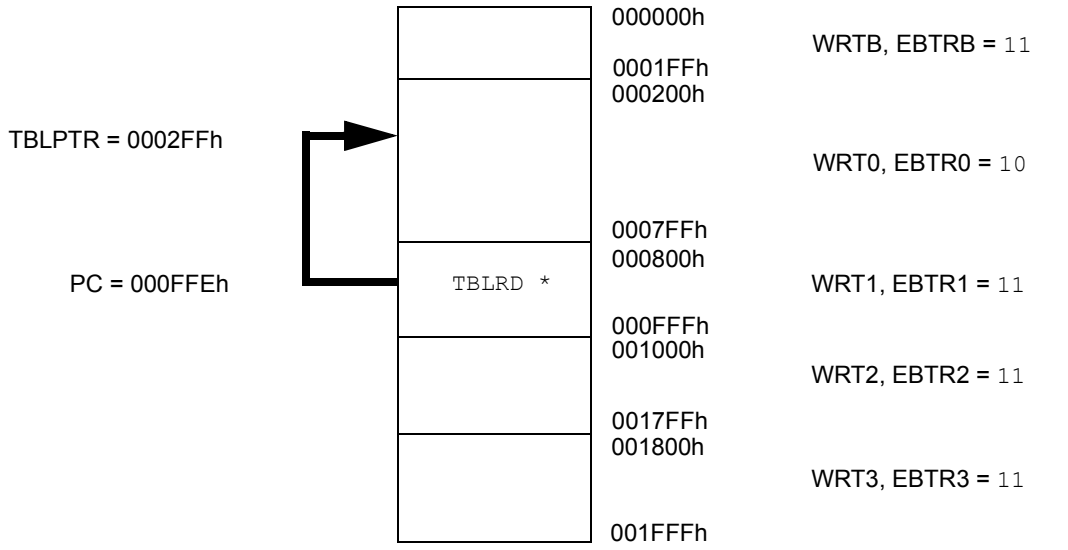
Entering a power-managed mode by loading the OSCCON register and executing a `SLEEP` instruction will clear the fail-safe condition. When the fail-safe condition is cleared, the clock monitor will resume monitoring the peripheral clock.

FIGURE 23-4: FSCM TIMING DIAGRAM



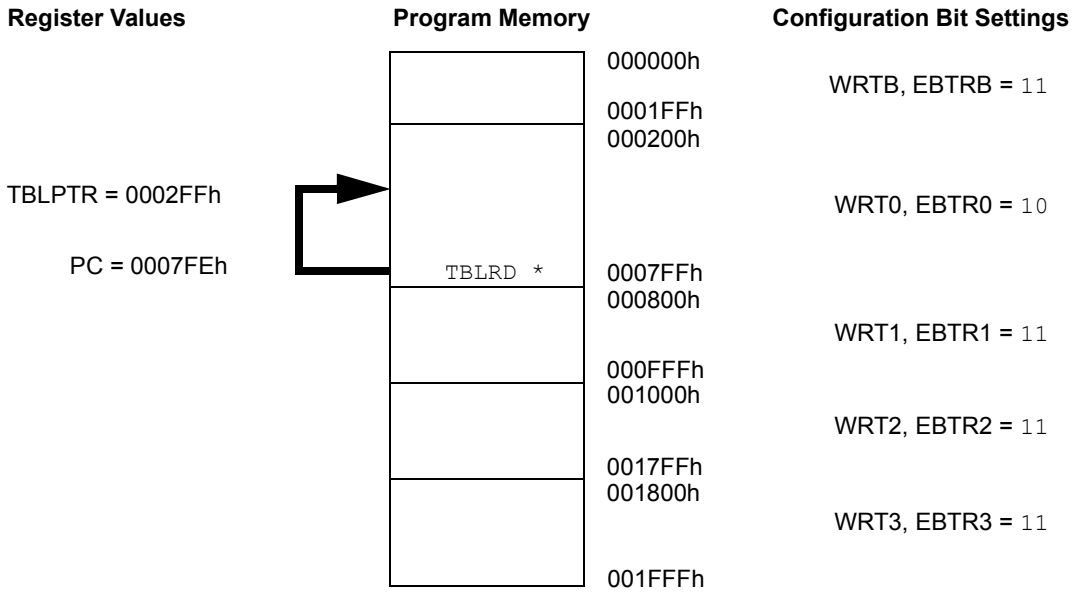
Note: The system clock is normally at a much higher frequency than the sample clock. The relative frequencies in this example have been chosen for clarity.

FIGURE 23-7: EXTERNAL BLOCK TABLE READ (EBTRx) DISALLOWED



Results: All table reads from external blocks to Blockn are disabled whenever EBTRx = 0.
TABLAT register returns a value of '0'.

FIGURE 23-8: EXTERNAL BLOCK TABLE READ (EBTRx) ALLOWED



Results: Table reads permitted within Blockn, even when EBTRBx = 0.
TABLAT register returns the value of the data at the location TBLPTR.

NOTES:

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 1048575$

Operation: $k \rightarrow PC<20:1>$

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	1111	k_7kkk	$kkkk_0$
2nd word(k<19:8>)	1111	$k_{19}kkk$	kkkk	$kkkk_8$

Description: GOTO allows an unconditional branch anywhere within entire 2 Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a two-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: GOTO THERE

After Instruction
PC = Address (THERE)

INCF **Increment f**

Syntax: [*label*] INCF f [,d [,a]]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0010	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default). If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: INCF CNT,

Before Instruction
CNT = 0xFF
Z = 0
C = ?
DC = ?

After Instruction
CNT = 0x00
Z = 1
C = 1
DC = 1

MOVLW **Move Literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow W$

Status Affected: None

Encoding:

0000	1110	kkkk	kkkk

Description: The eight-bit literal 'k' is loaded into W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example: `MOVLW 0x5A`

After Instruction

W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f [,a]

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: $(W) \rightarrow f$

Status Affected: None

Encoding:

0110	111a	ffff	ffff

Description: Move data from W to register 'f'. Location 'f' can be anywhere in the 256-byte bank. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `MOVWF REG`

Before Instruction

W = 0x4F
REG = 0xFF

After Instruction

W = 0x4F
REG = 0x4F

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2220/2320/4220/4320 (Industrial) PIC18LF2220/2320/4220/4320 (Industrial) (Continued)

PIC18LF2220/2320/4220/4320 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F2220/2320/4220/4320 (Industrial, Extended)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2,3)						
	PIC18LF2X20/4X20	440	600	µA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**PRI_RUN**, EC oscillator)
		450	600	µA	+25°C		
		460	600	µA	+85°C		
	PIC18LF2X20/4X20	0.80	1.0	mA	-40°C	VDD = 3.0V	
		0.78	1.0	mA	+25°C		
		0.77	1.0	mA	+85°C		
	All devices	1.6	2.0	mA	-40°C	VDD = 5.0V	
		1.5	2.0	mA	+25°C		
		1.5	2.0	mA	+85°C		
	Extended devices	1.5	2.0	mA	+125°C		
	Extended devices	6.3	9.0	mA	+125°C	VDD = 4.2V	FOSC = 25 MHz (**PRI_RUN**, EC oscillator)
		7.9	10.0	mA	+125°C	VDD = 5.0V	
	All devices	9.5	12	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz (**PRI_RUN**, EC oscillator)
		9.7	12	mA	+25°C		
		9.9	12	mA	+85°C		
	All devices	11.9	15	mA	-40°C	VDD = 5.0V	
		12.1	15	mA	+25°C		
		12.3	15	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

4: Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

FIGURE 27-5: MAXIMUM IDD vs. FOSC OVER VDD PRI_RUN, EC MODE, -40°C TO +125°C

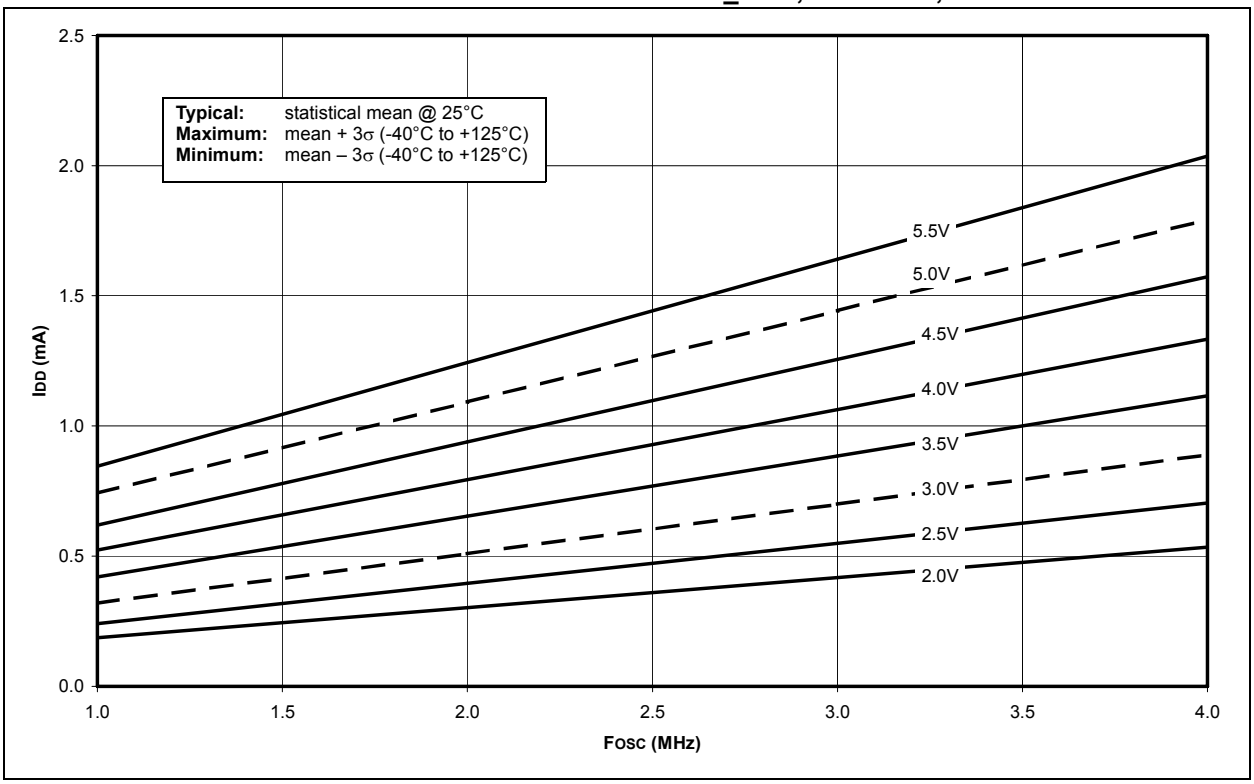


FIGURE 27-6: TYPICAL IDD vs. FOSC OVER VDD PRI_RUN, EC MODE, +25°C